





COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP10655	REV: E1	SUN REV: Not In VersionControl
	TID #: PMP10655		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11/30/2017 3:49:11 PM		TEXAS INSTRUMENTS

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